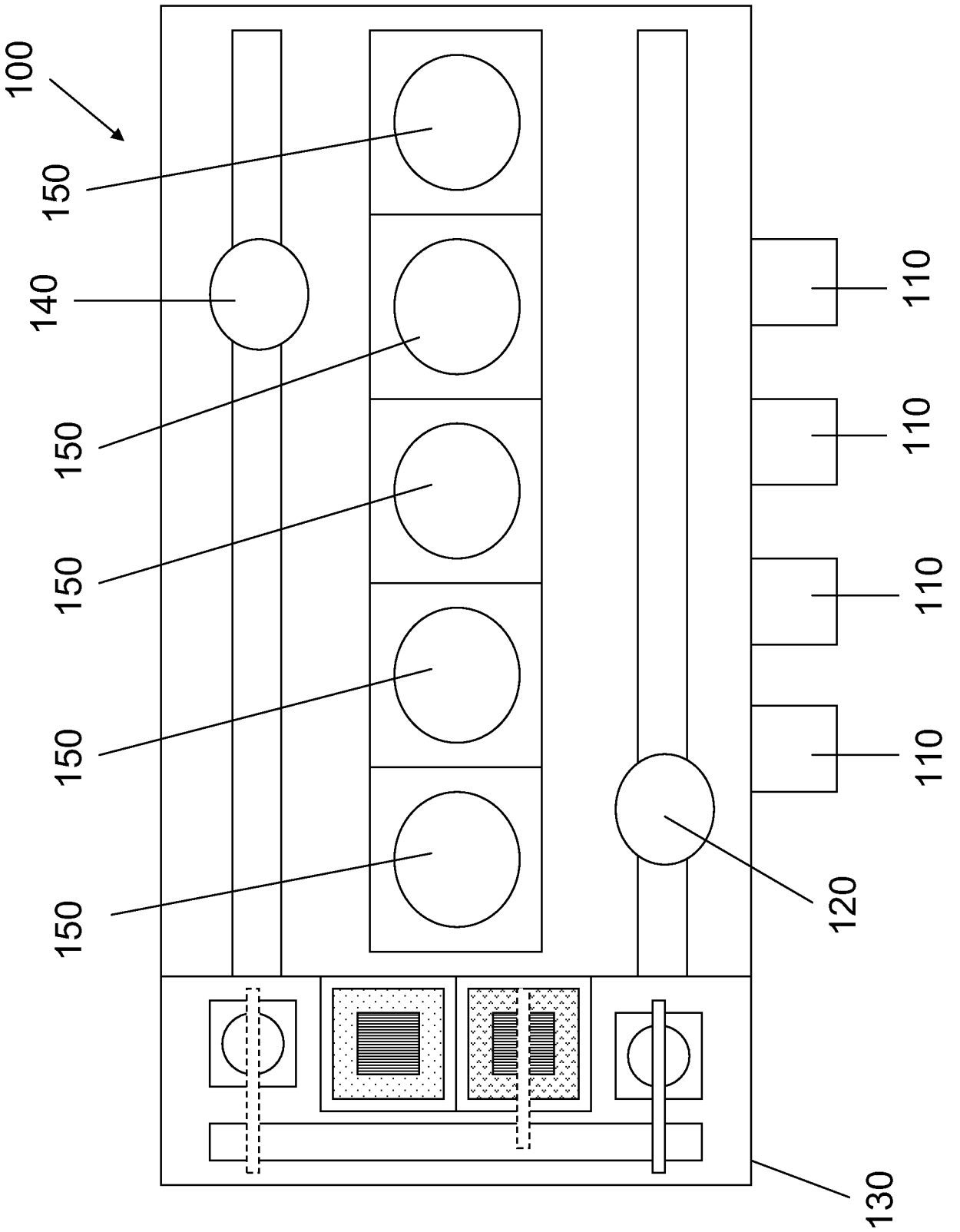



FIG. 1

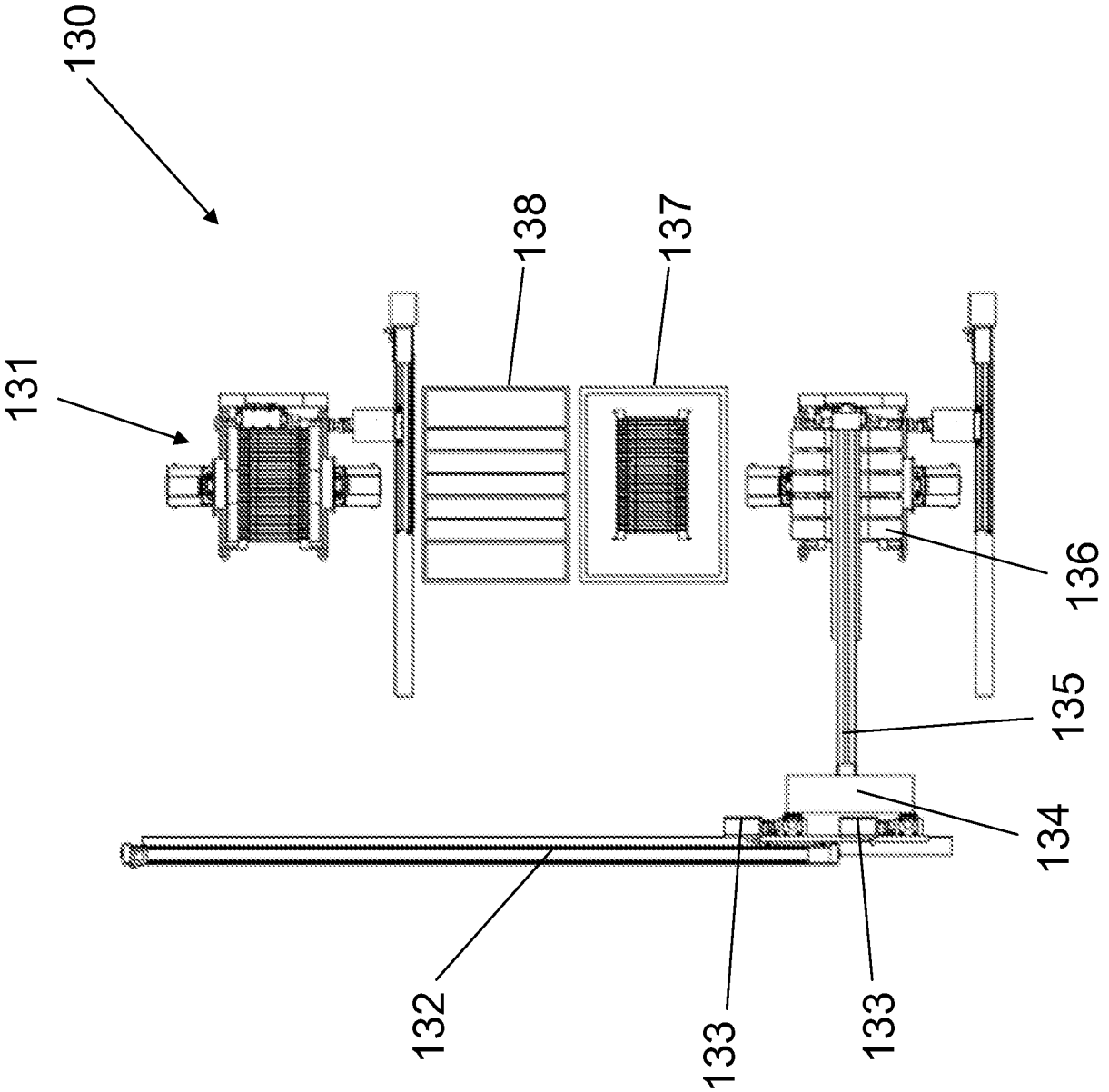



FIG. 2

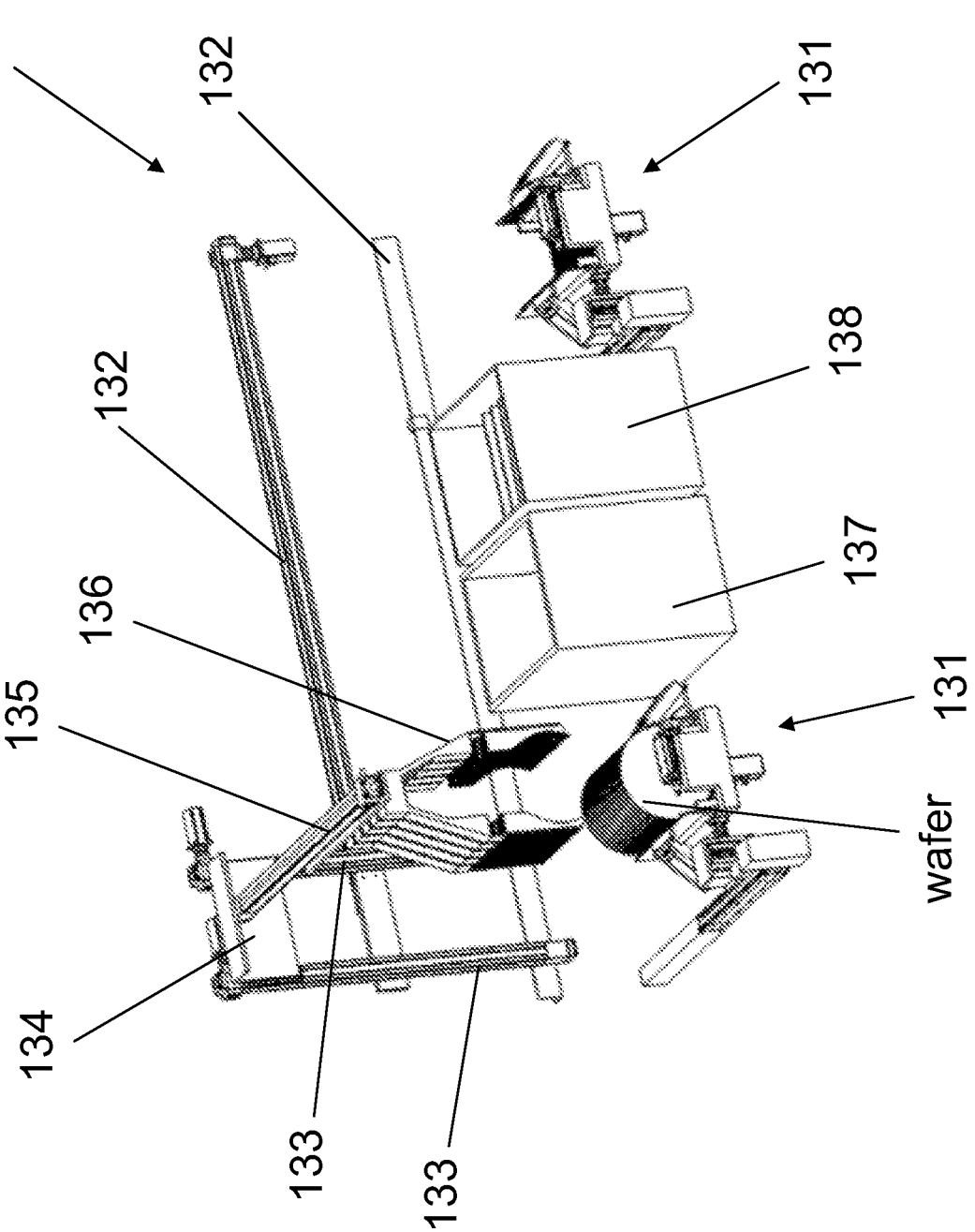



FIG. 3

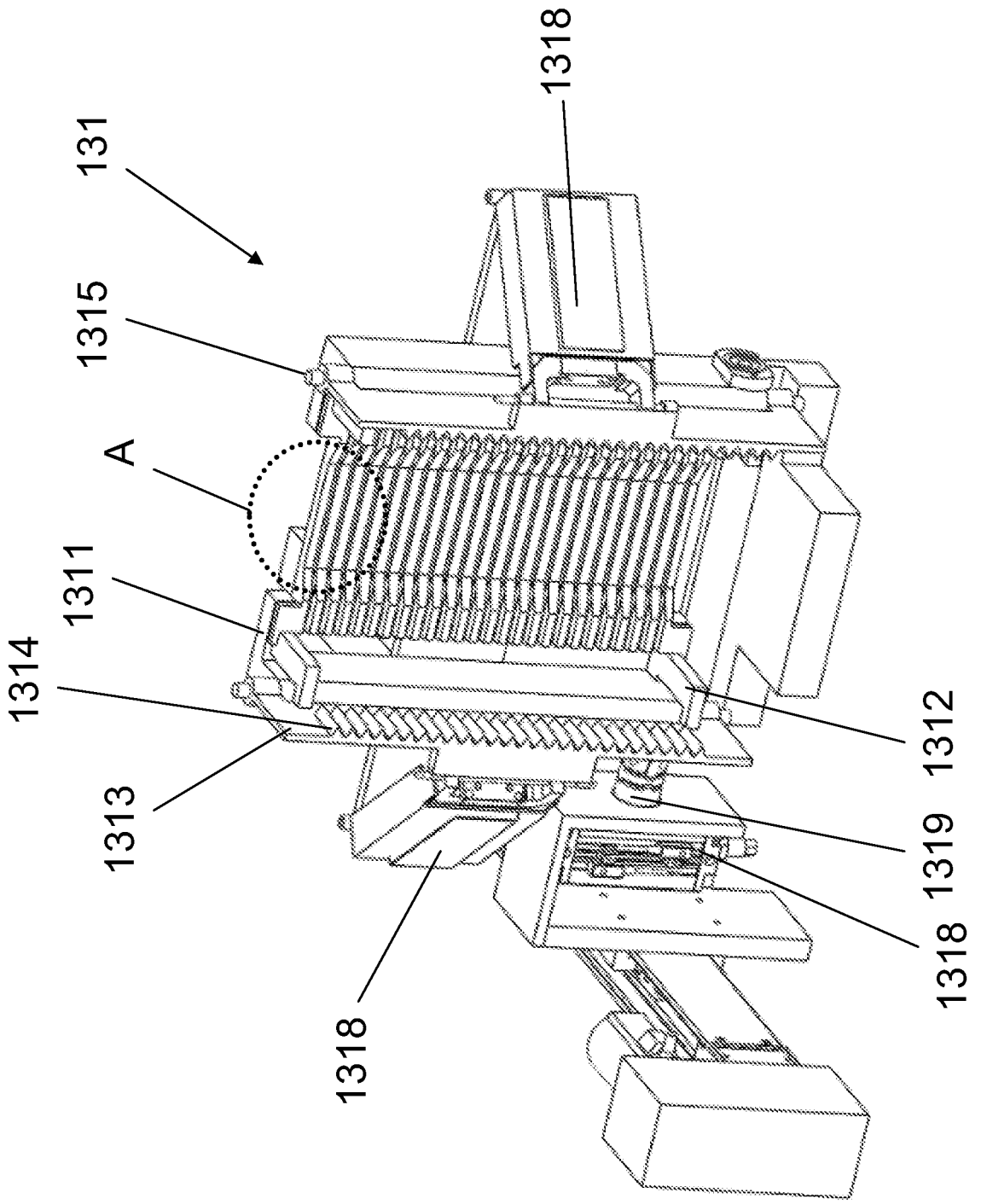



FIG. 4

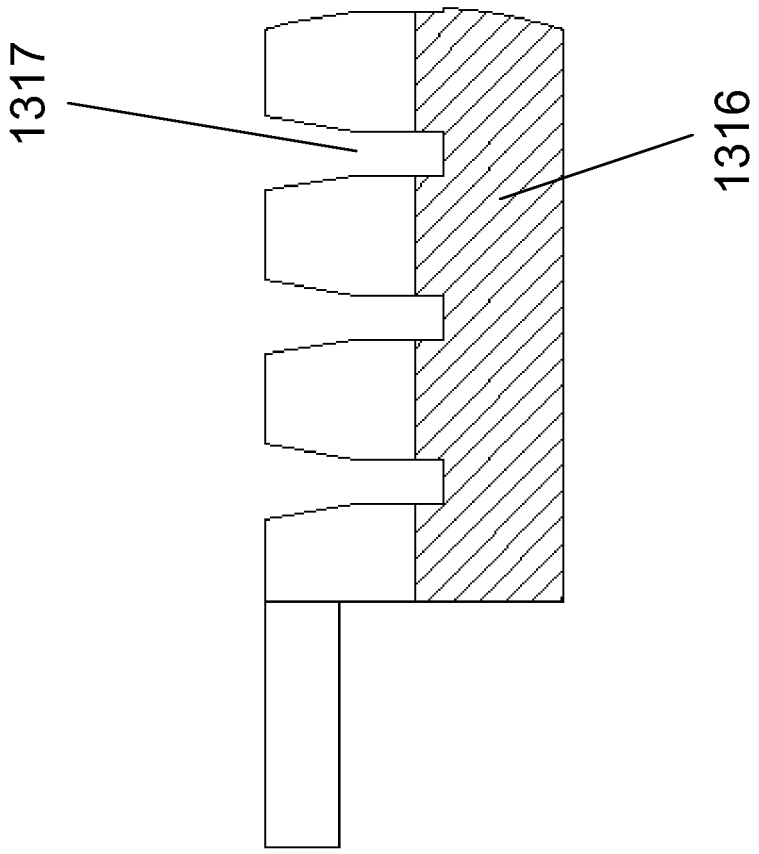



FIG. 5

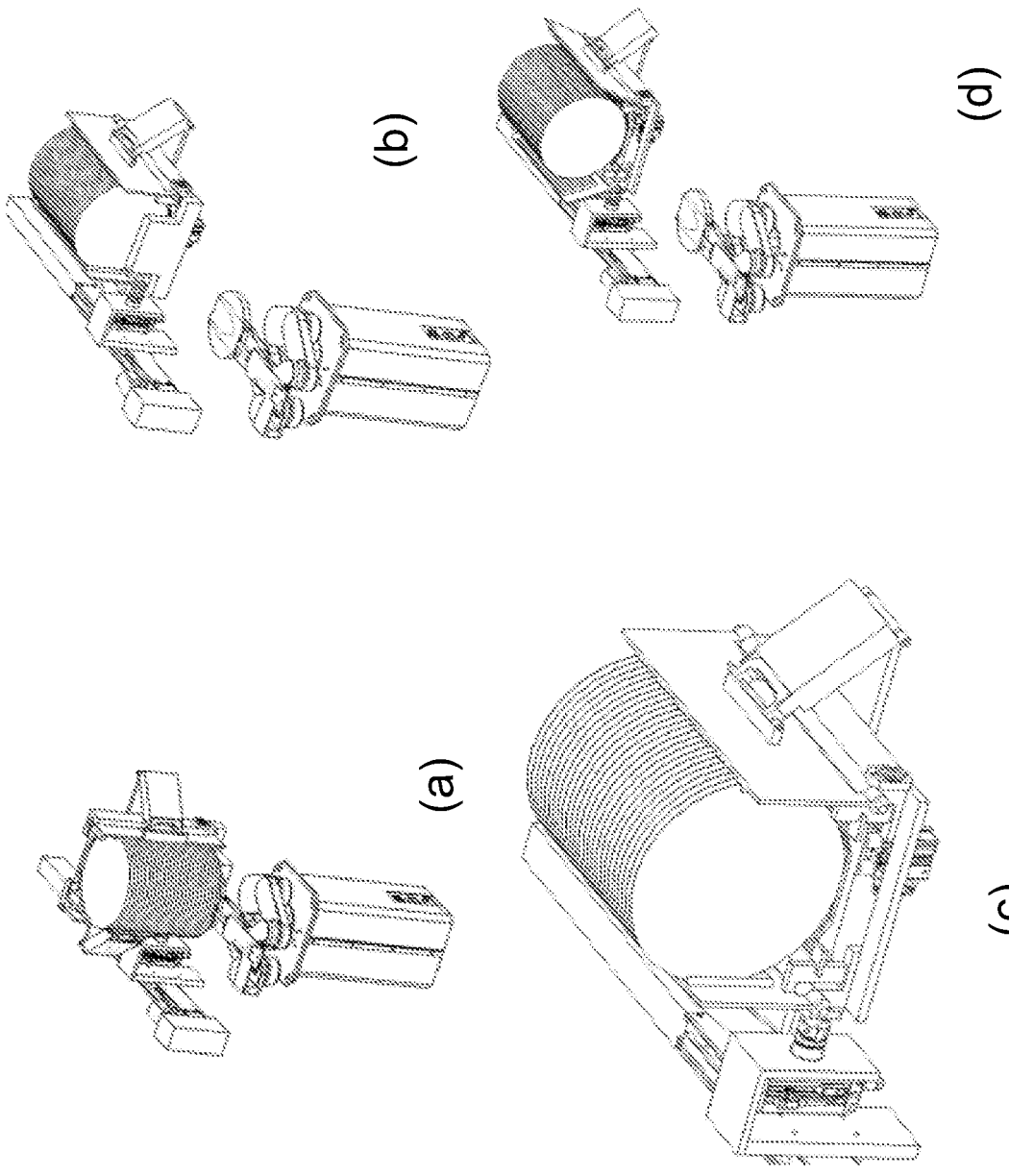



FIG. 6

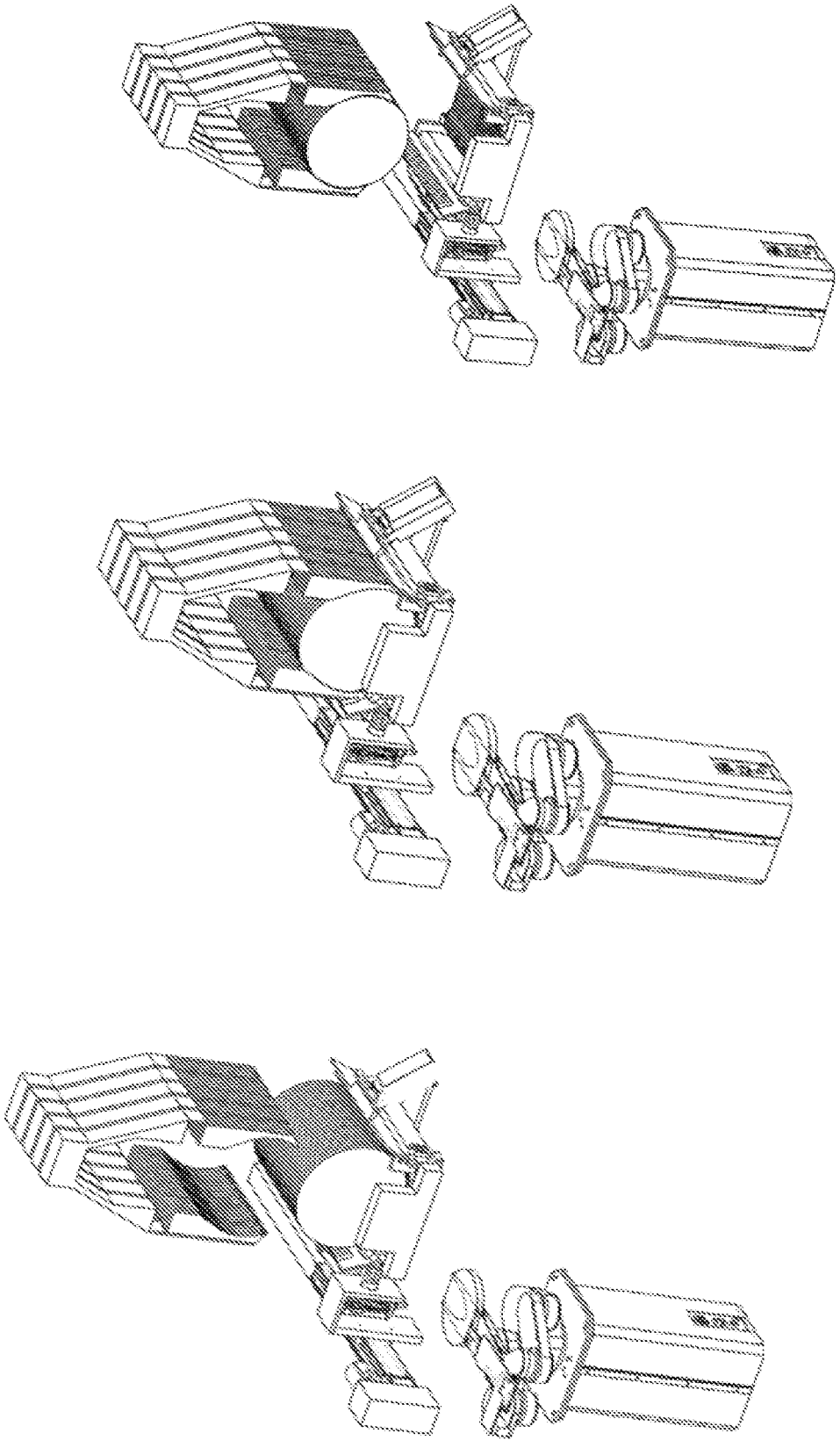



FIG. 7

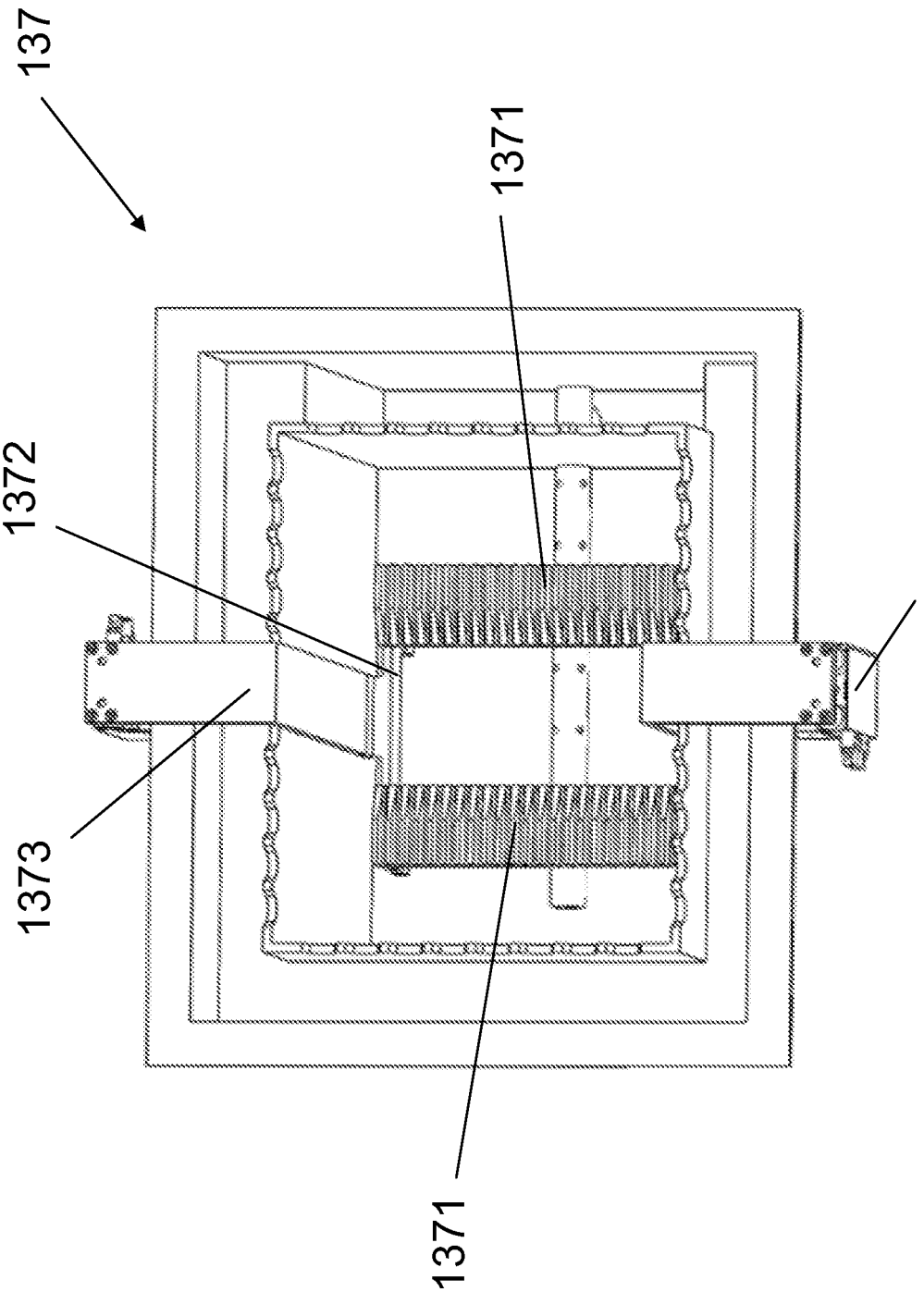



FIG. 8(a)

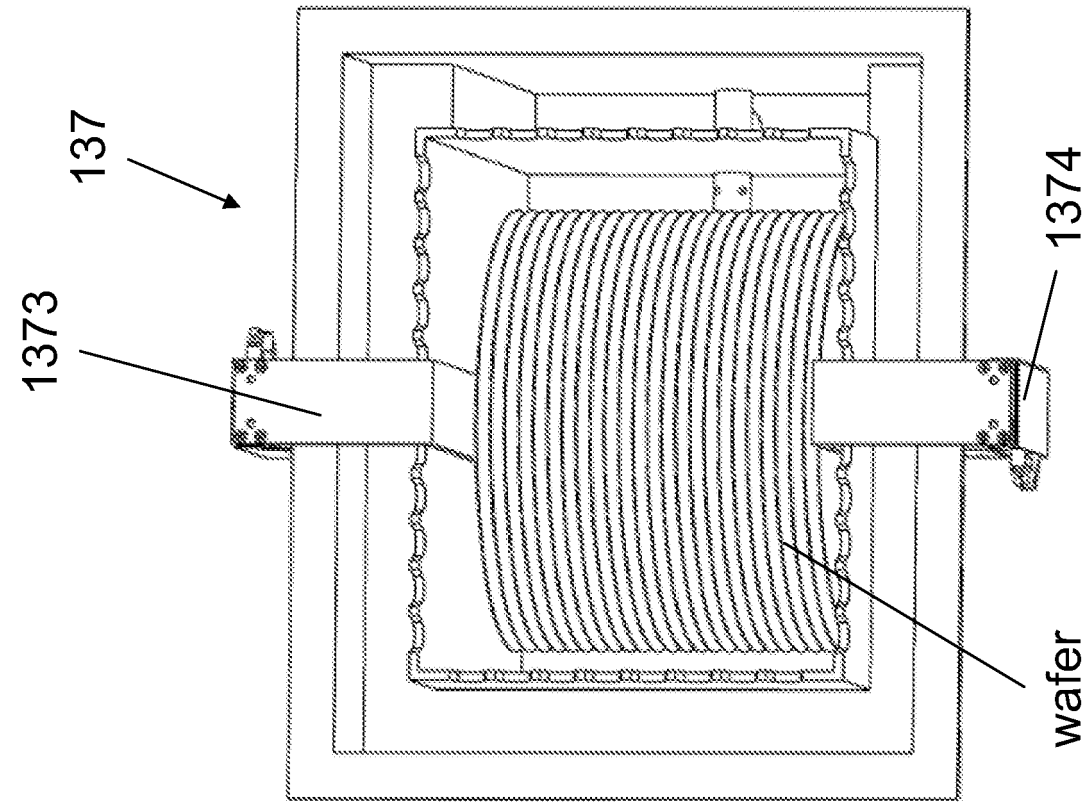



FIG. 8(c)

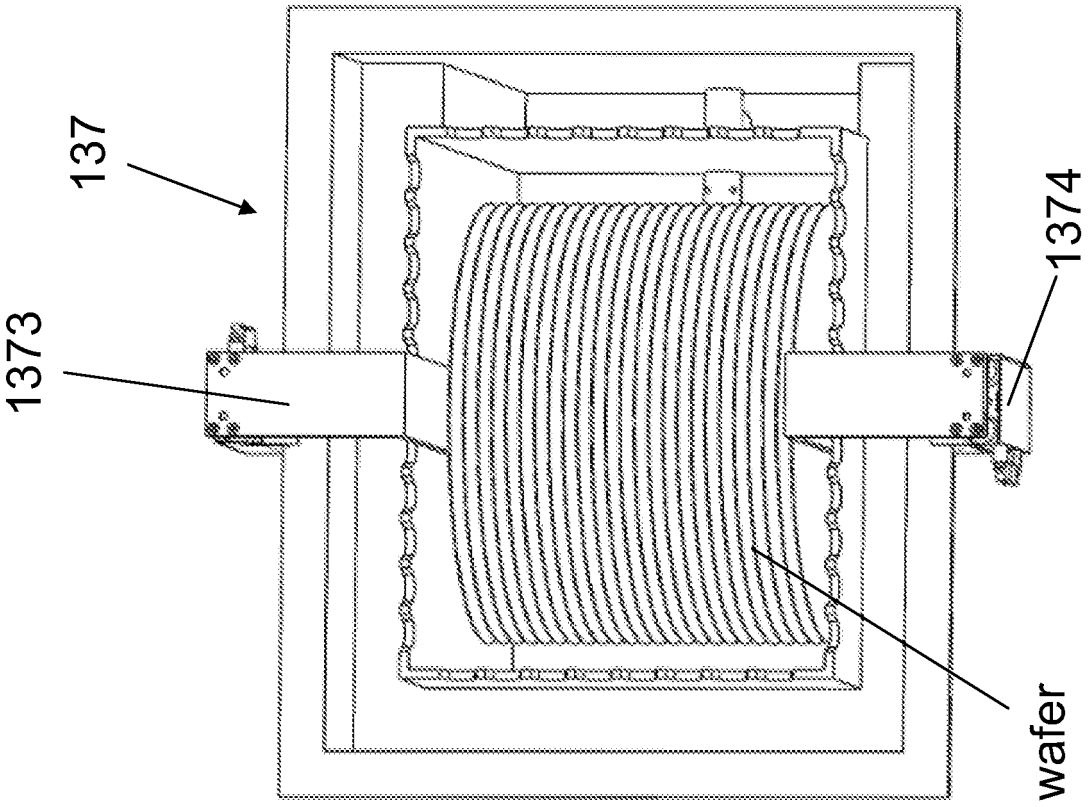



FIG. 8(b)

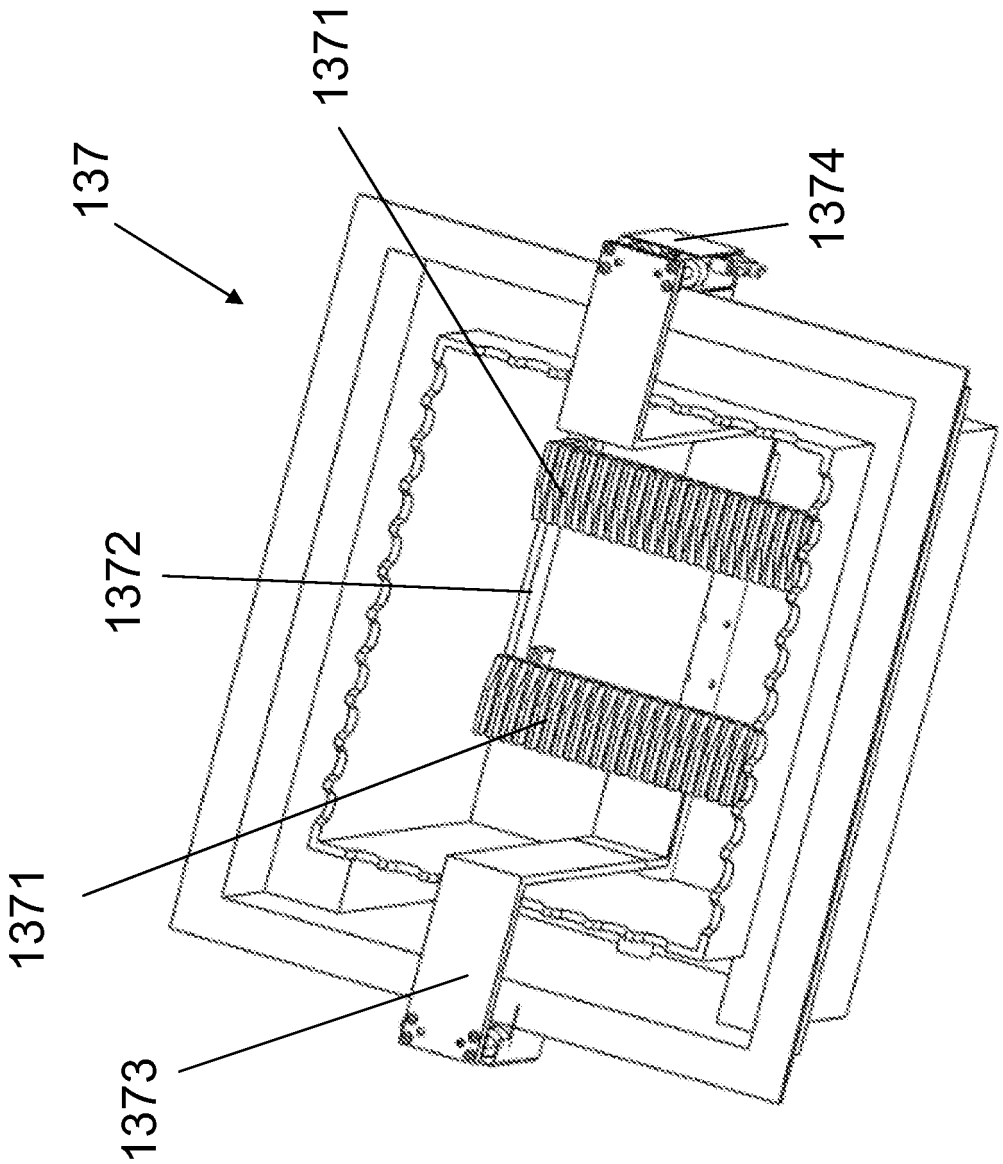



FIG. 9

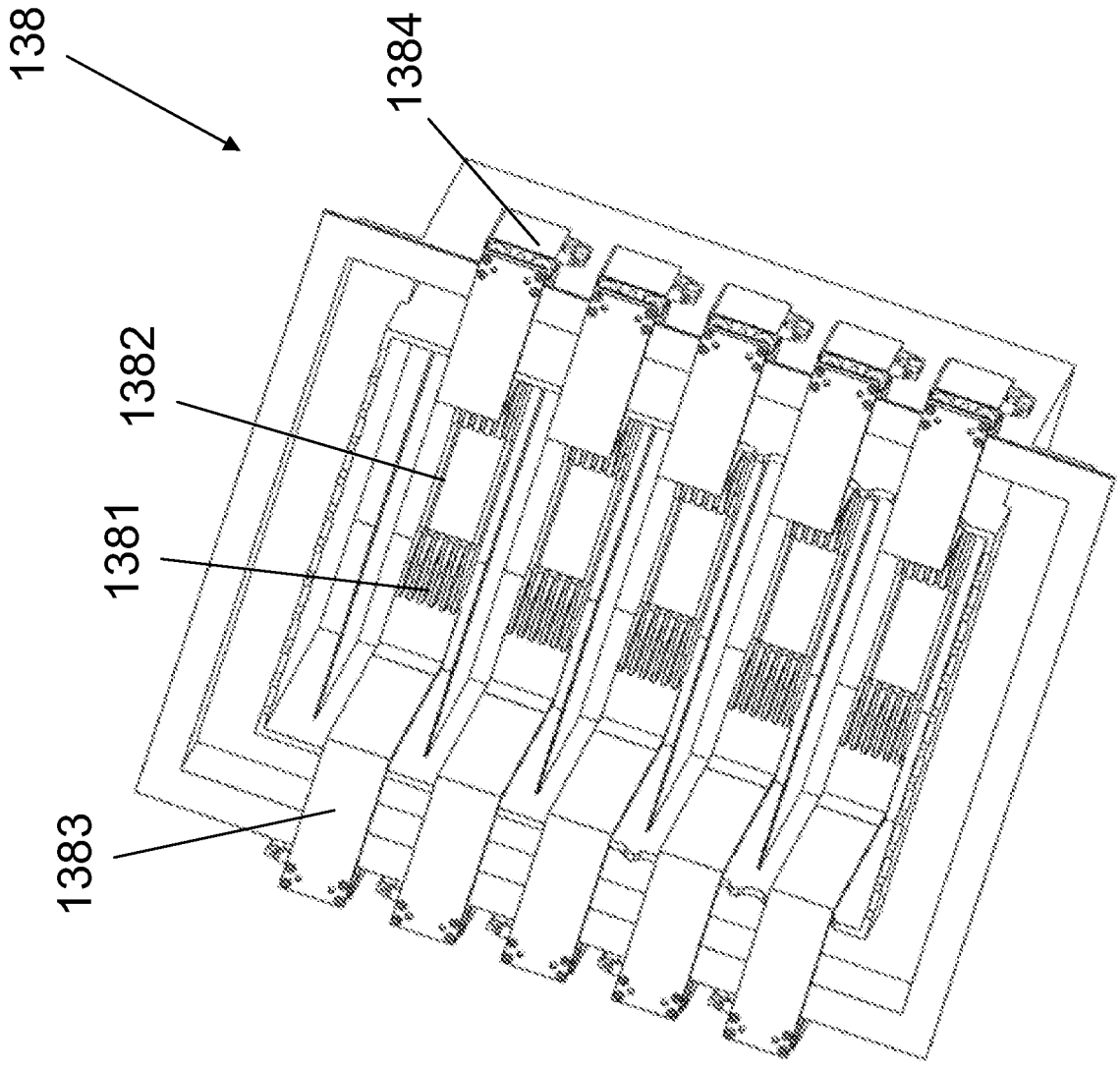



FIG. 10(a)

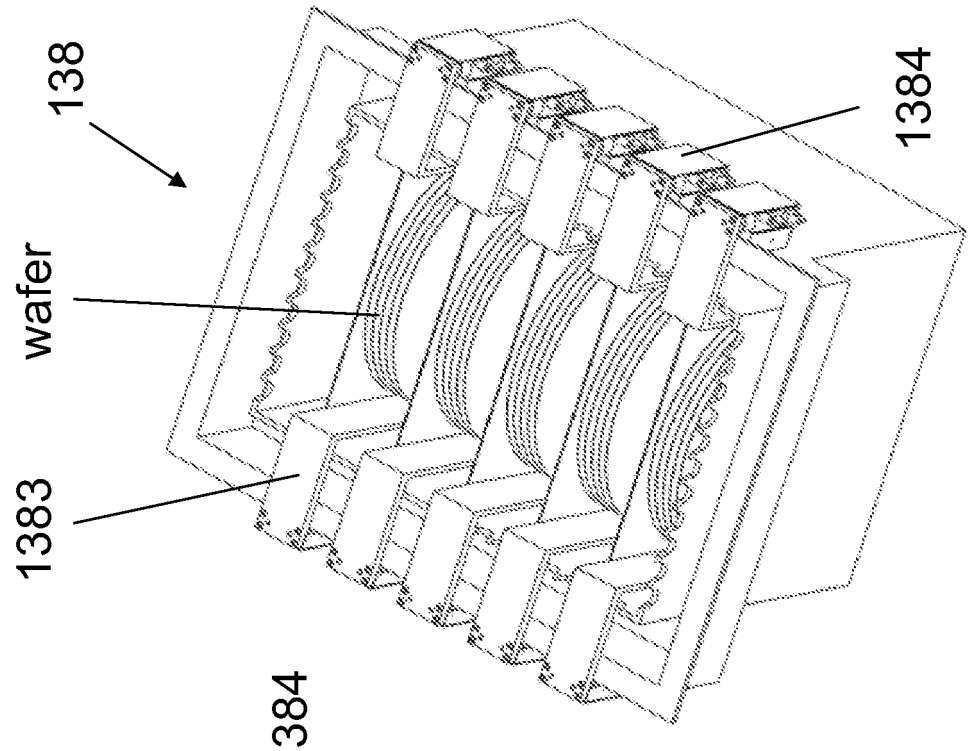



FIG. 10(c)

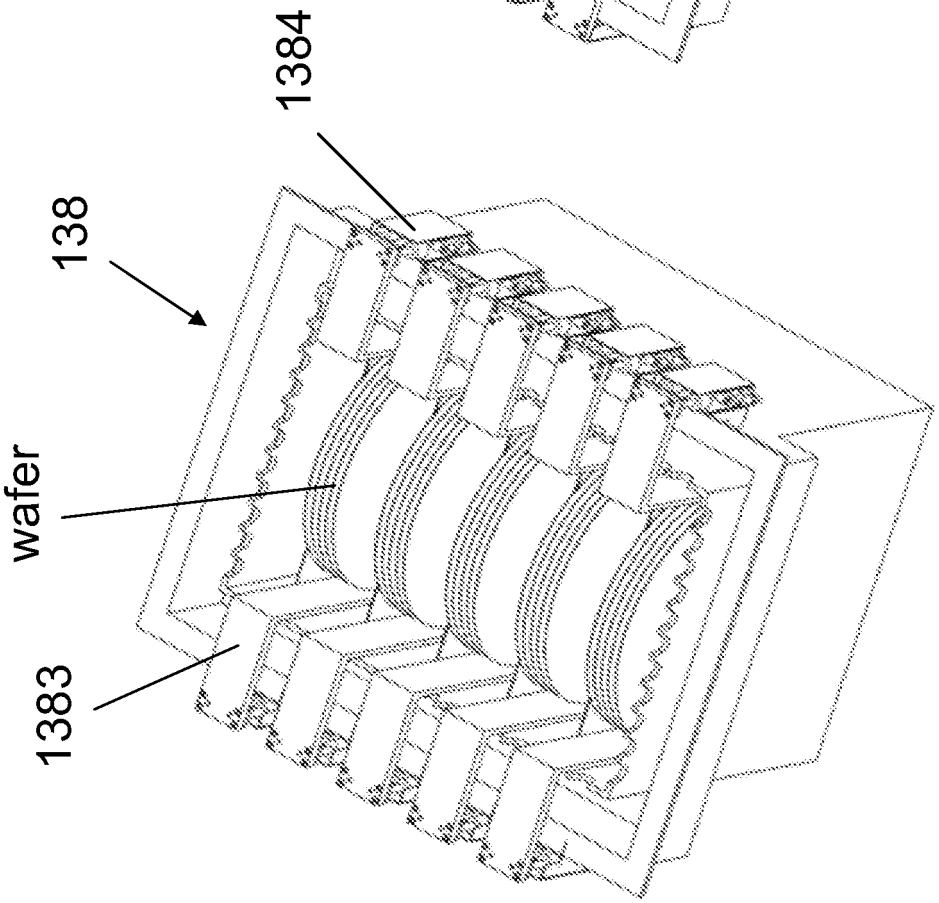



FIG. 10(b)

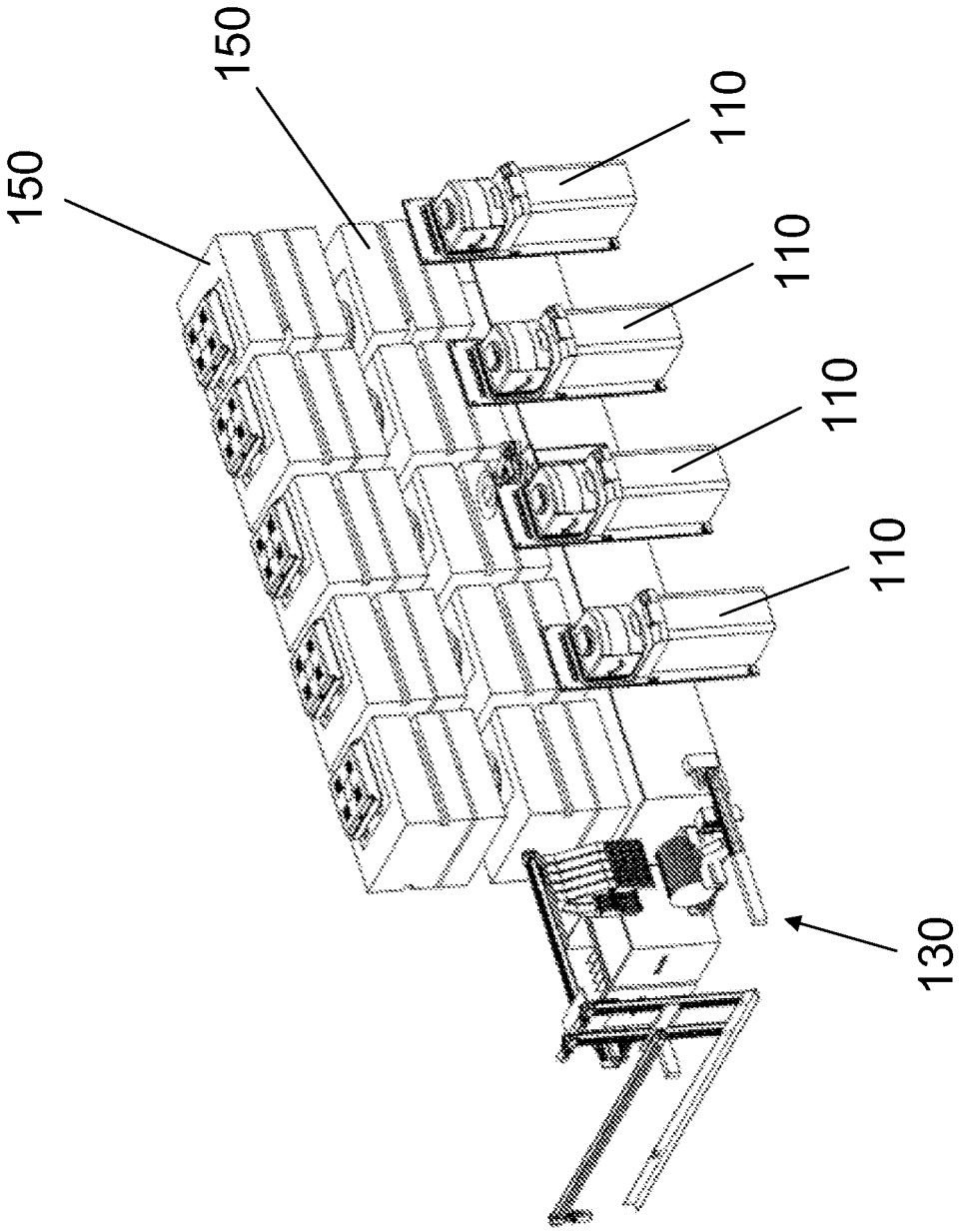



FIG. 11

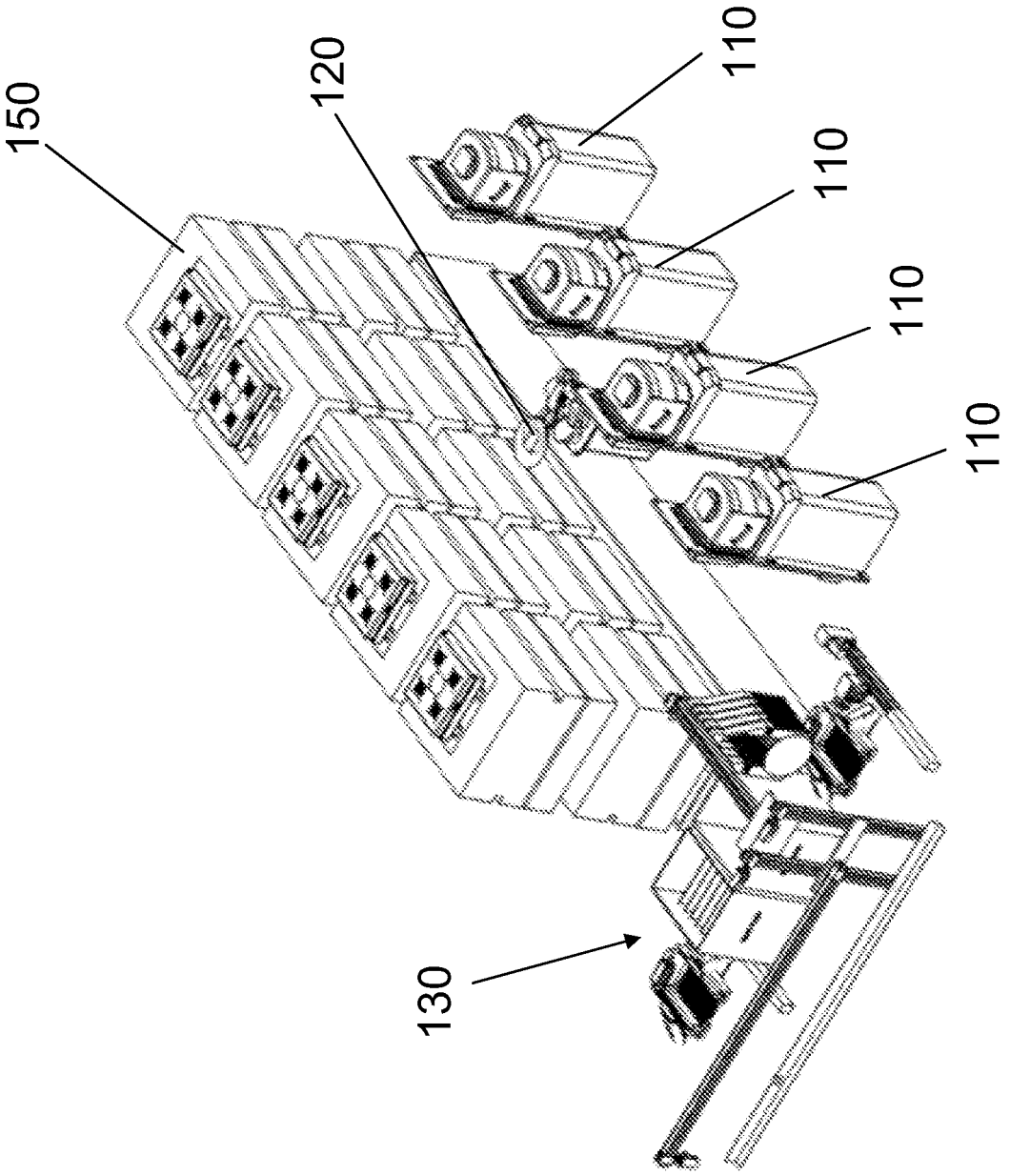



FIG. 12

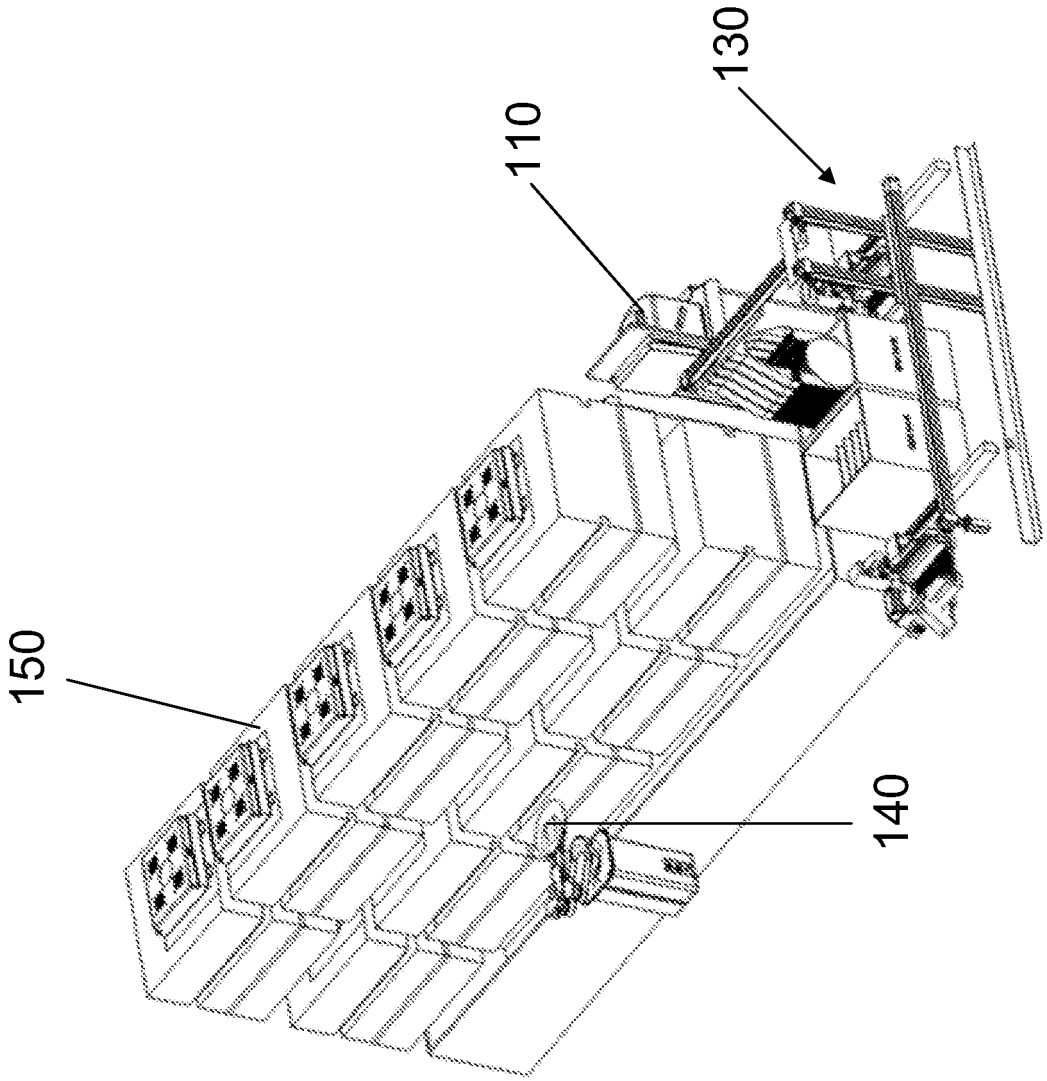



FIG. 13

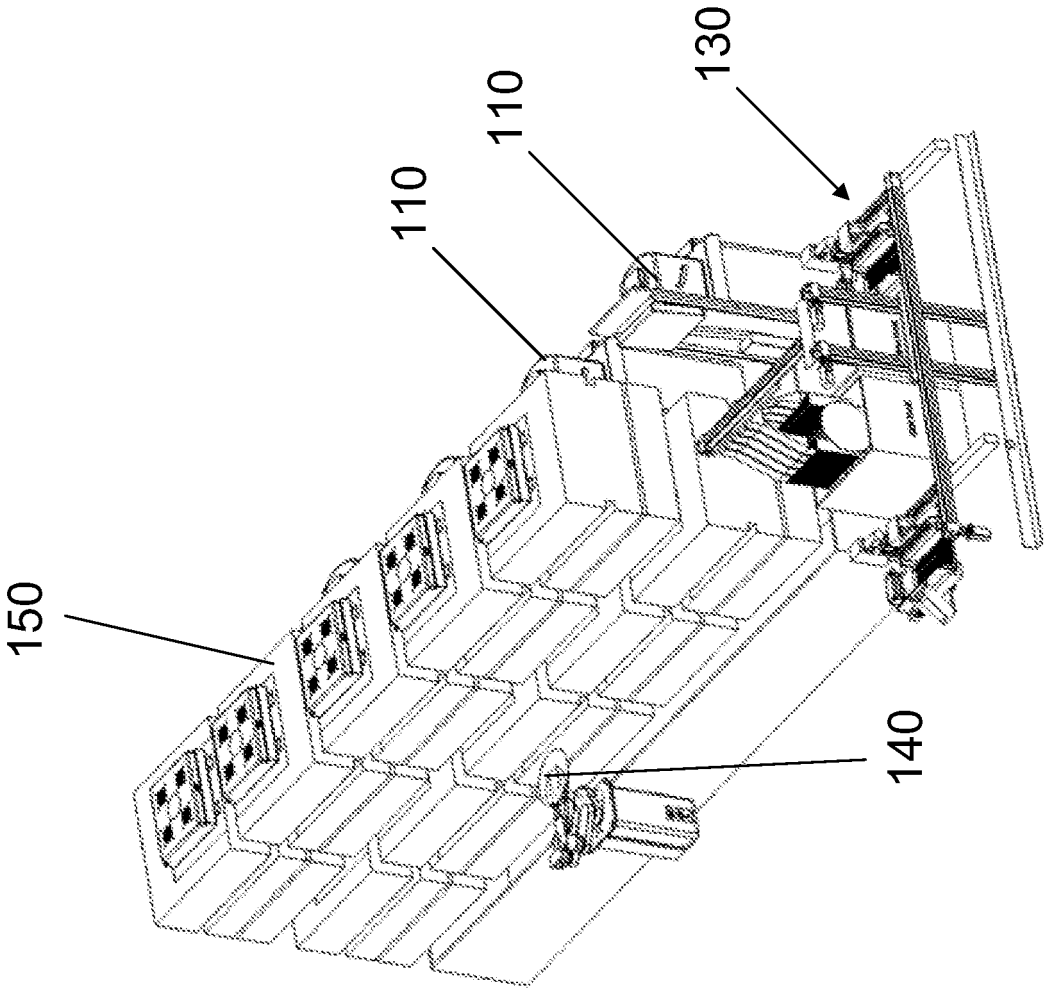



FIG. 14

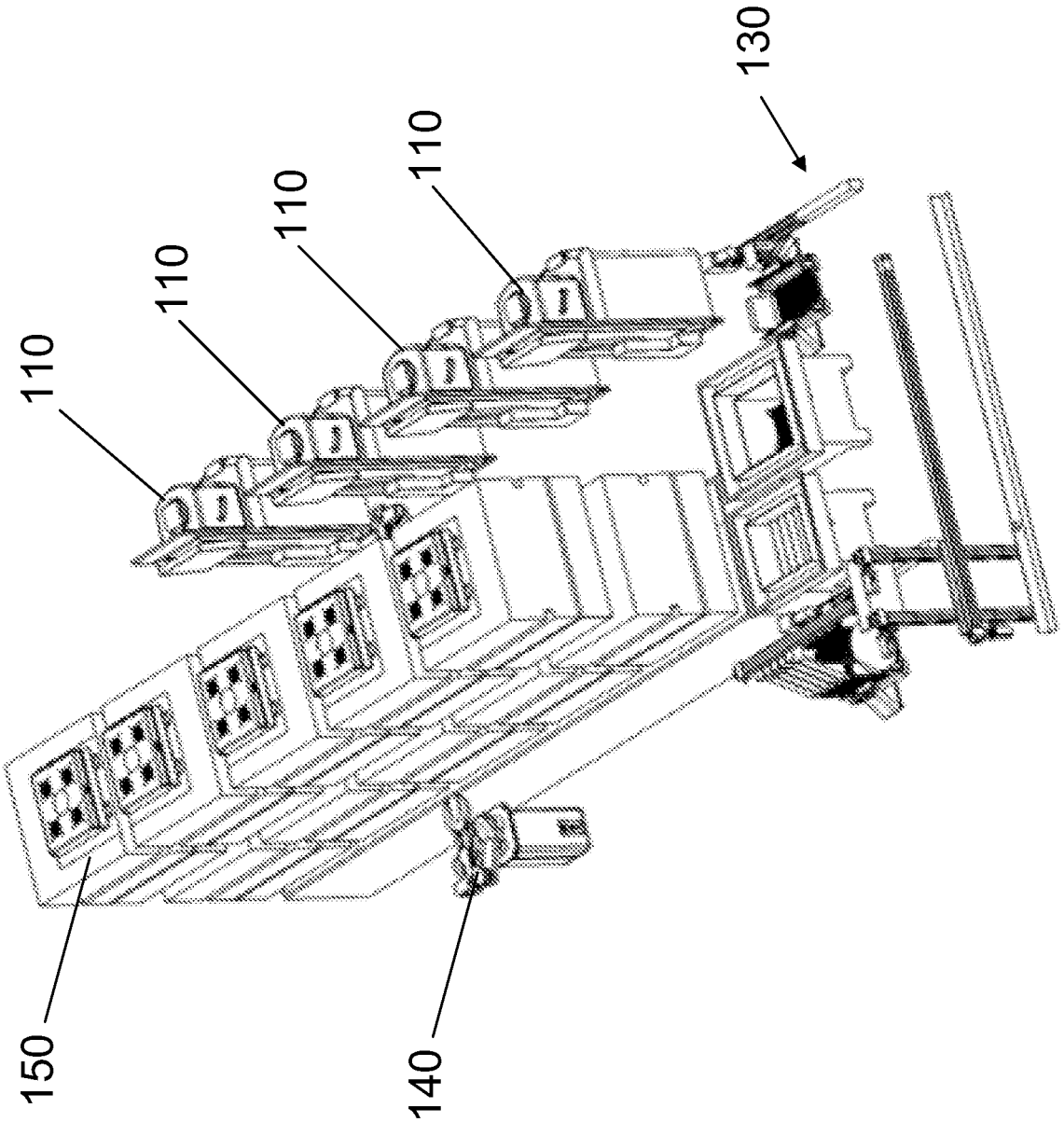



FIG. 15

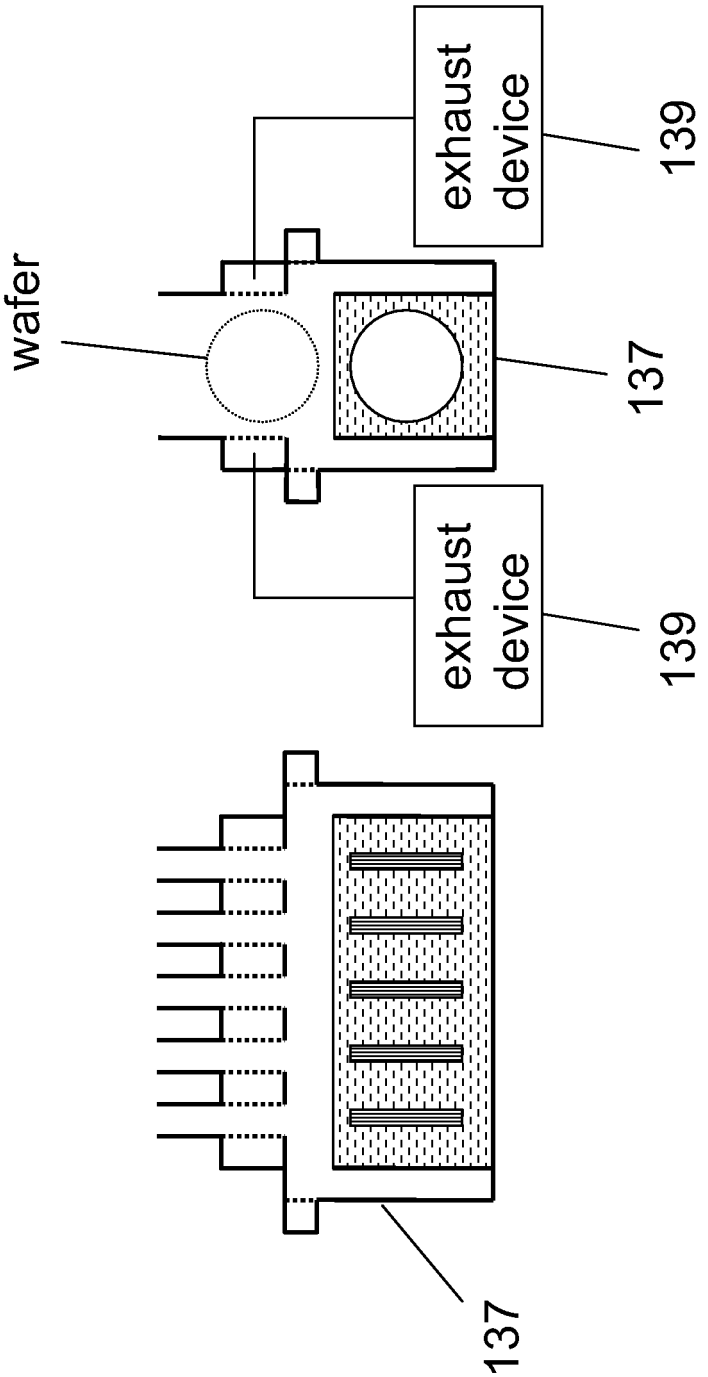



FIG. 16

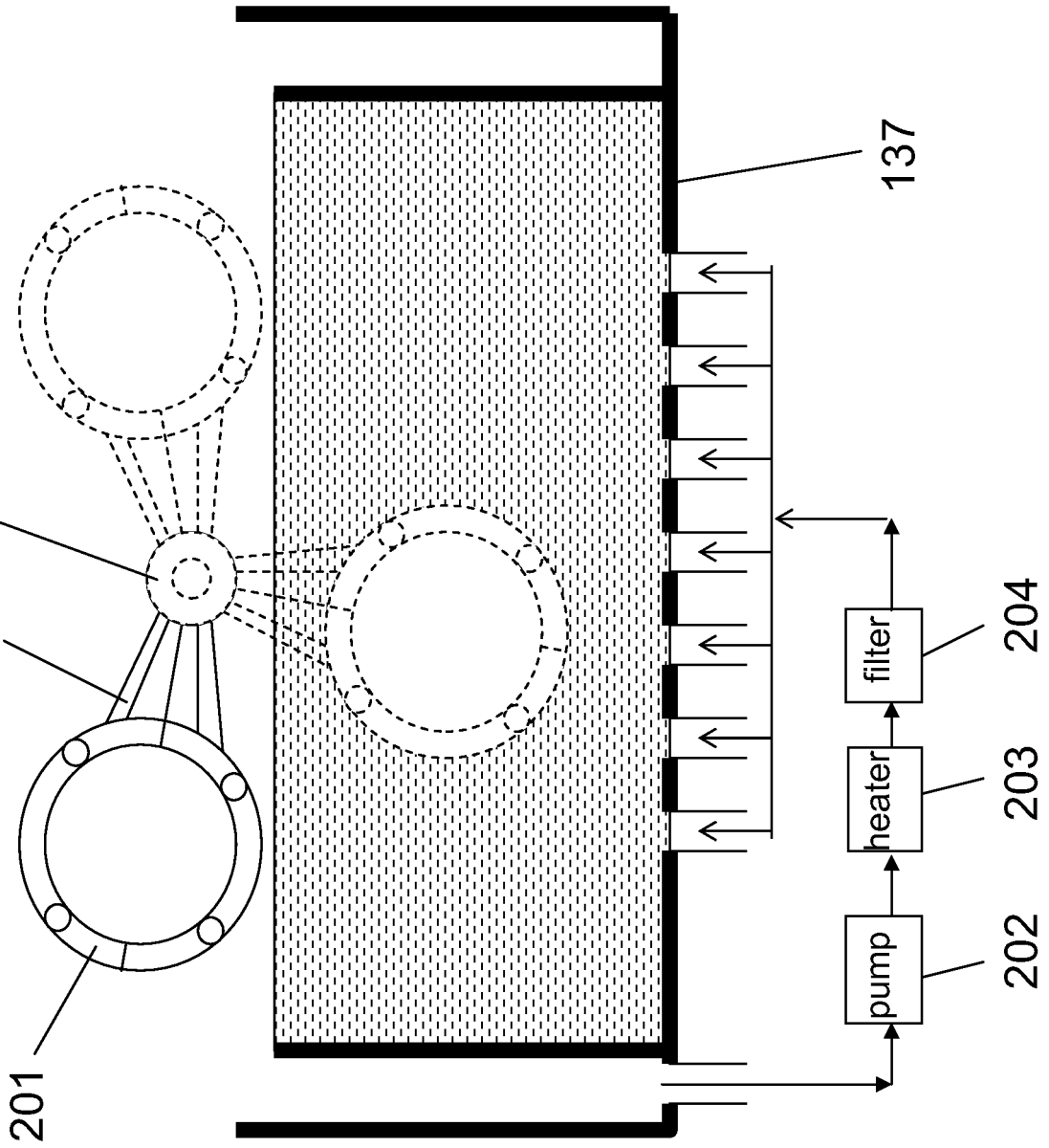



FIG. 17

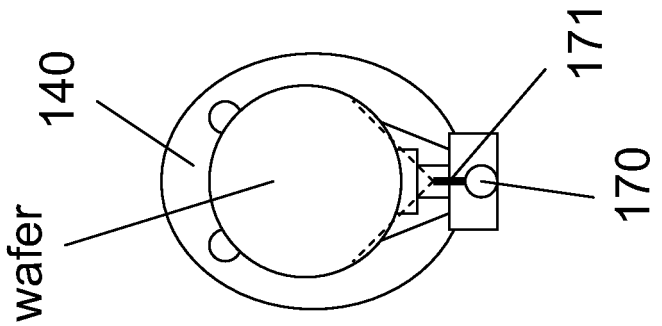



FIG. 20

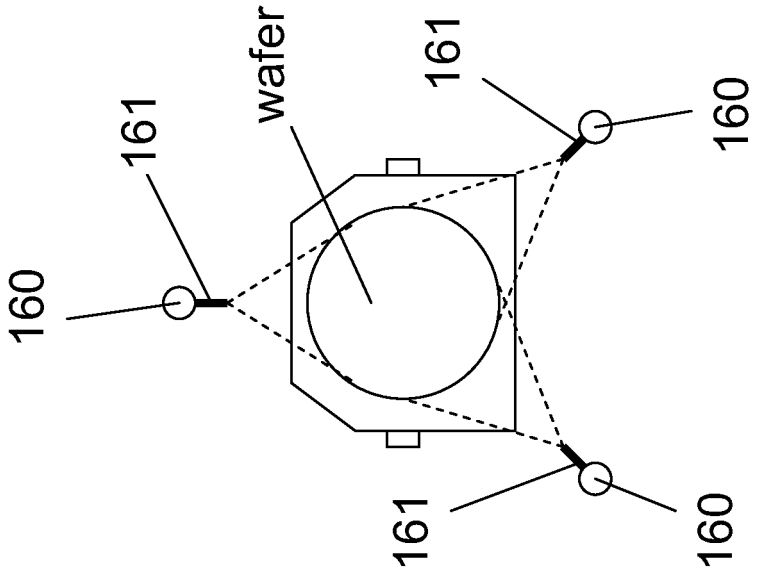



FIG. 19

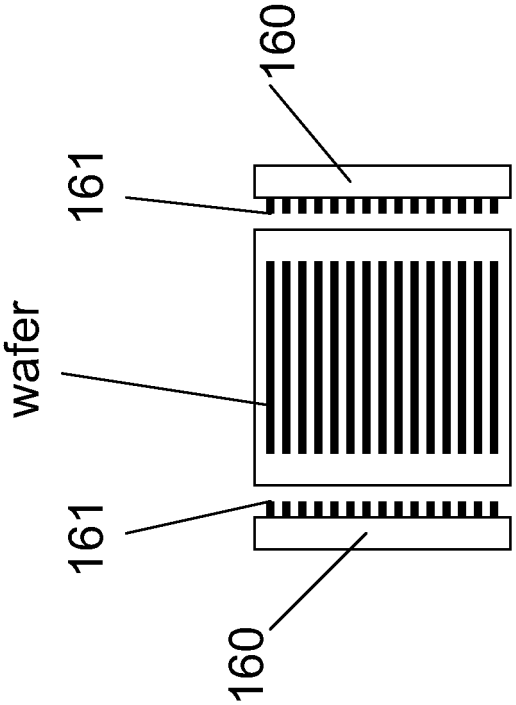



FIG. 18

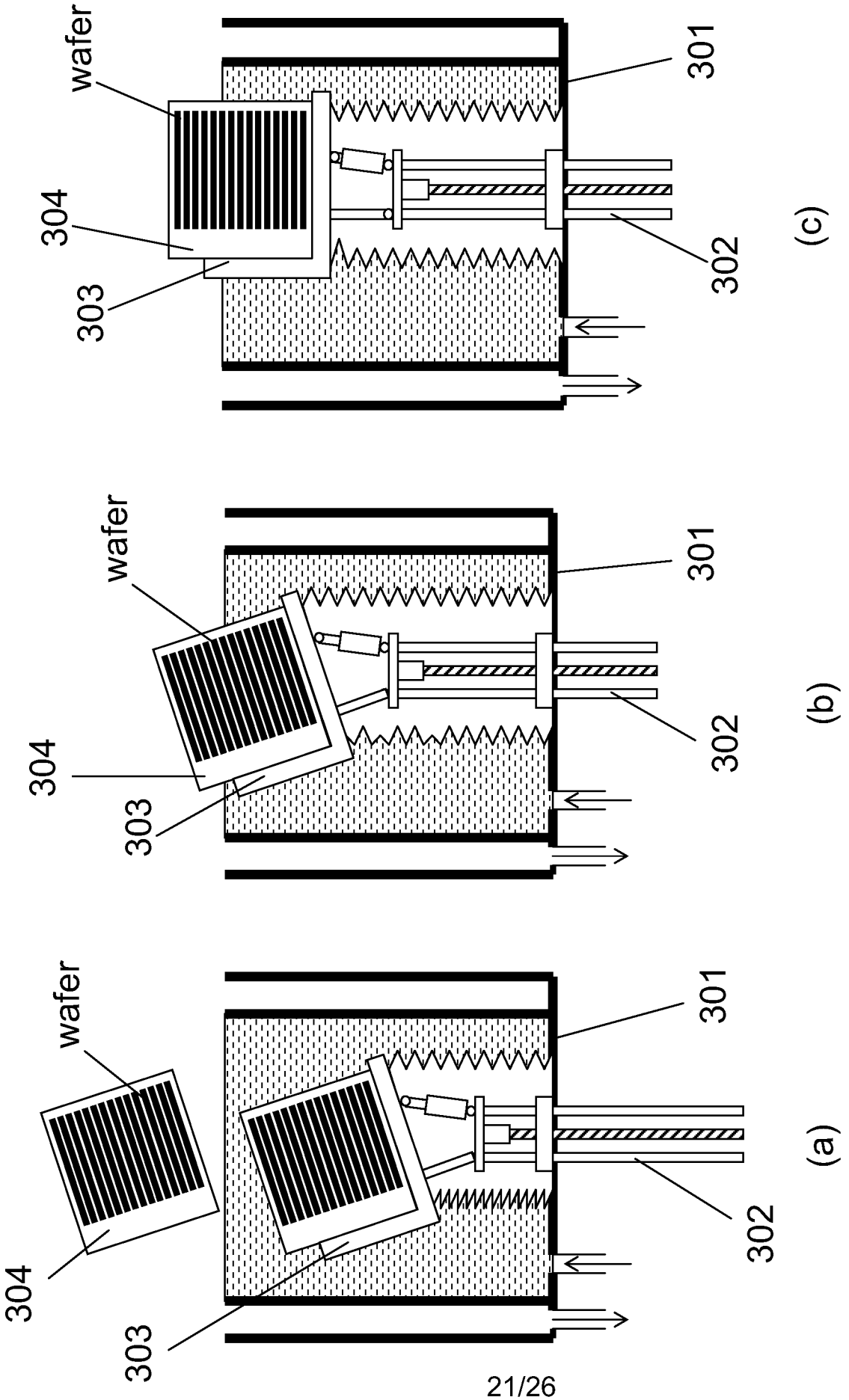

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FIG. 21

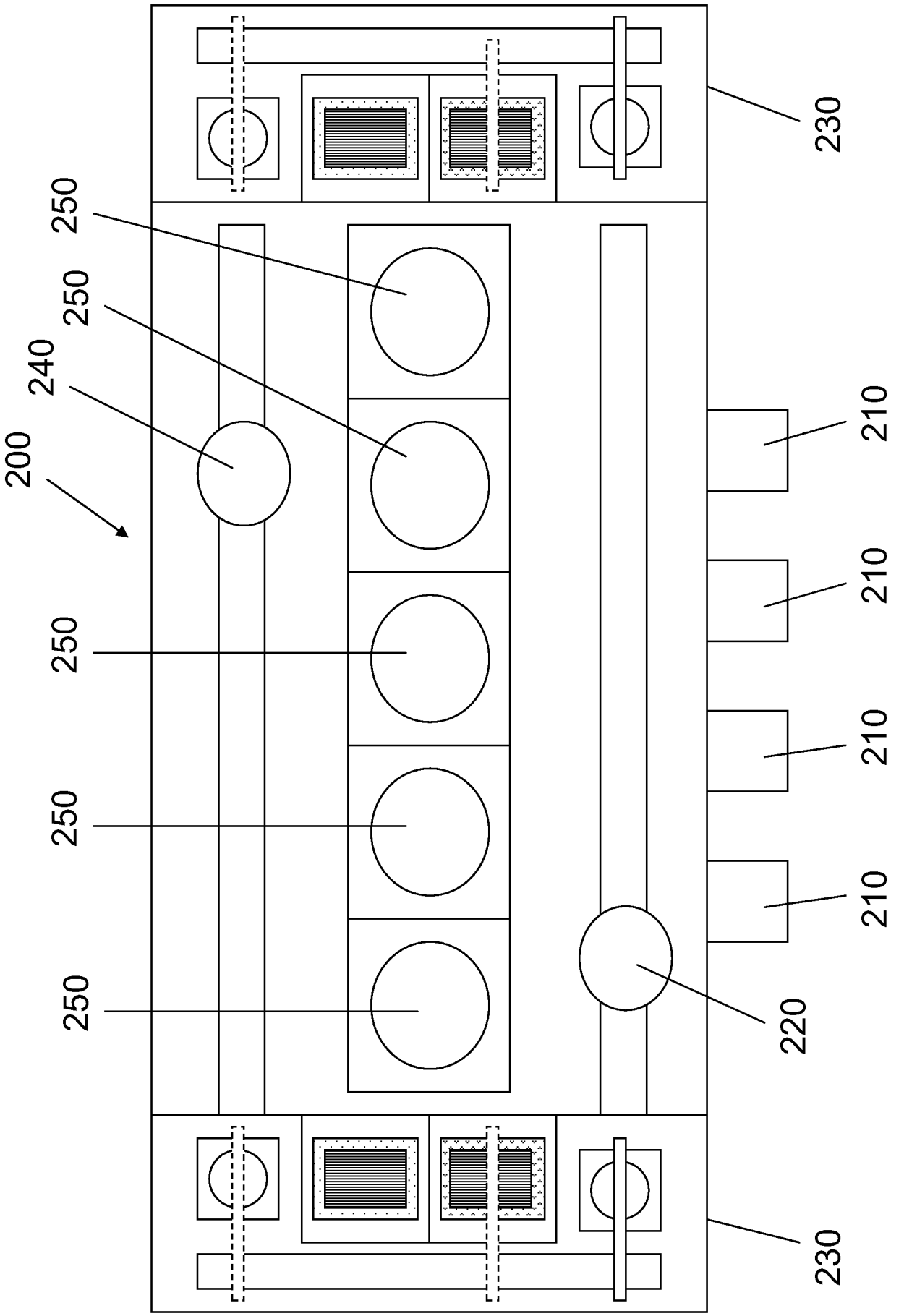



FIG. 22

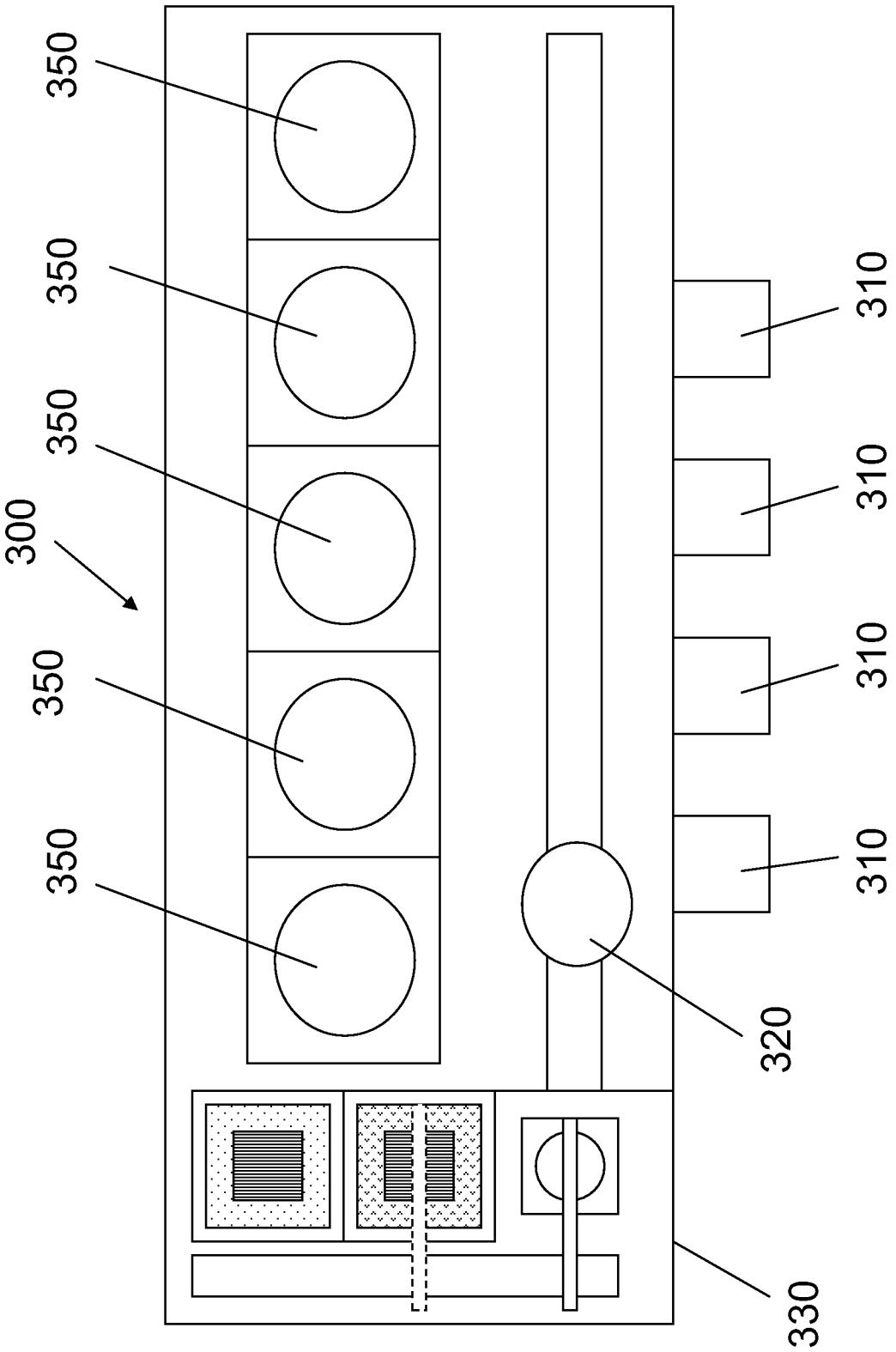



FIG. 23

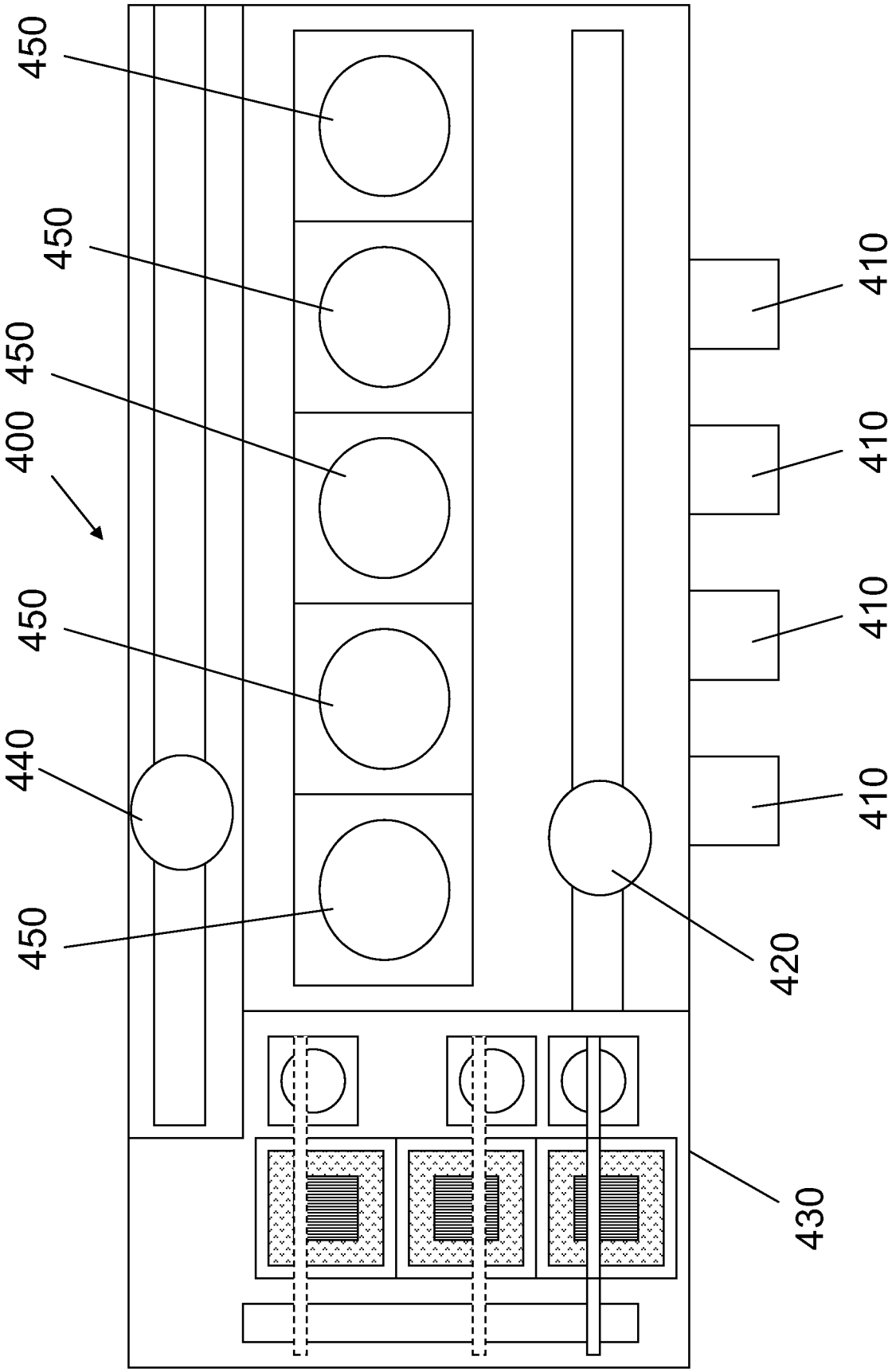



FIG. 24

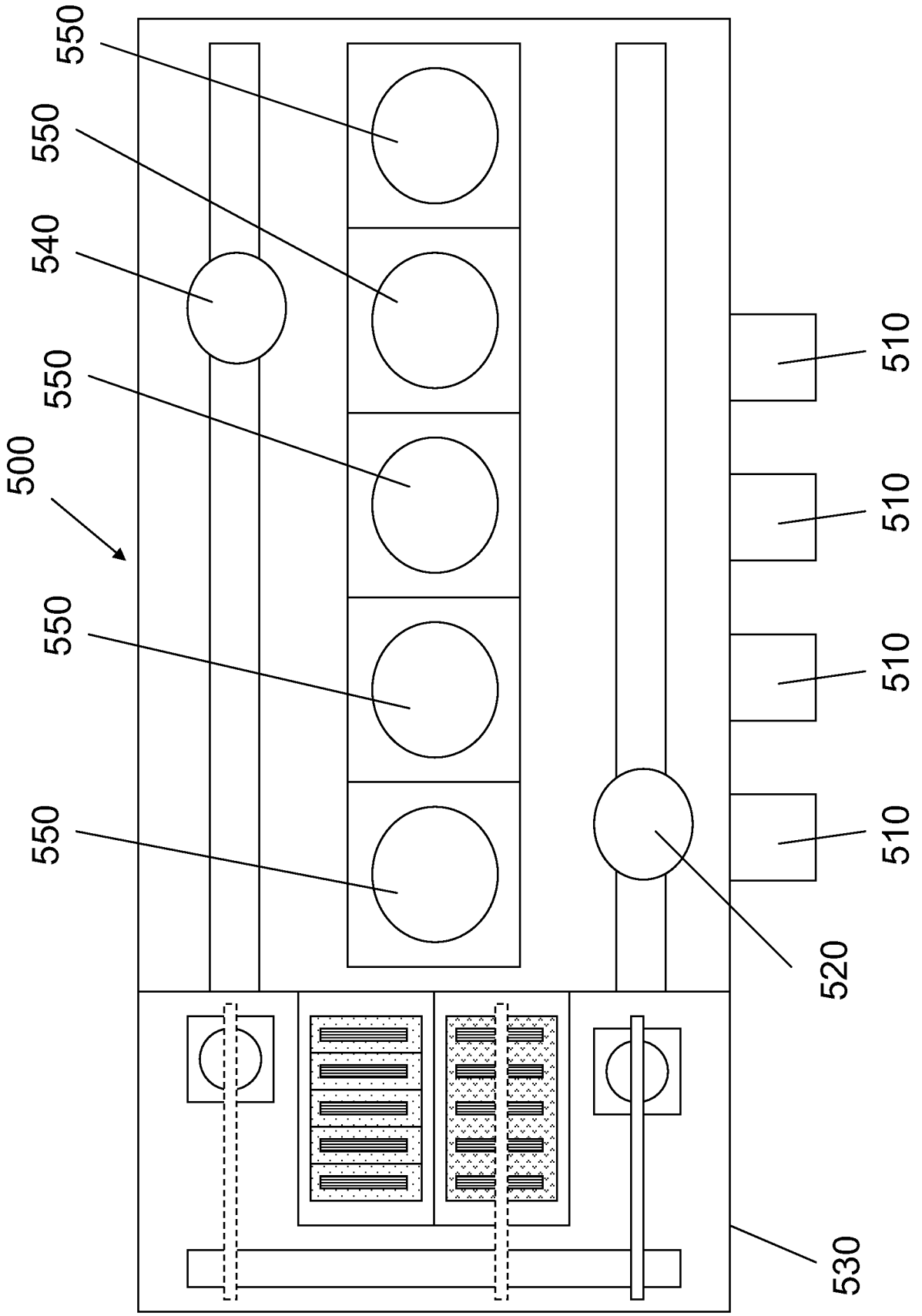



FIG. 25

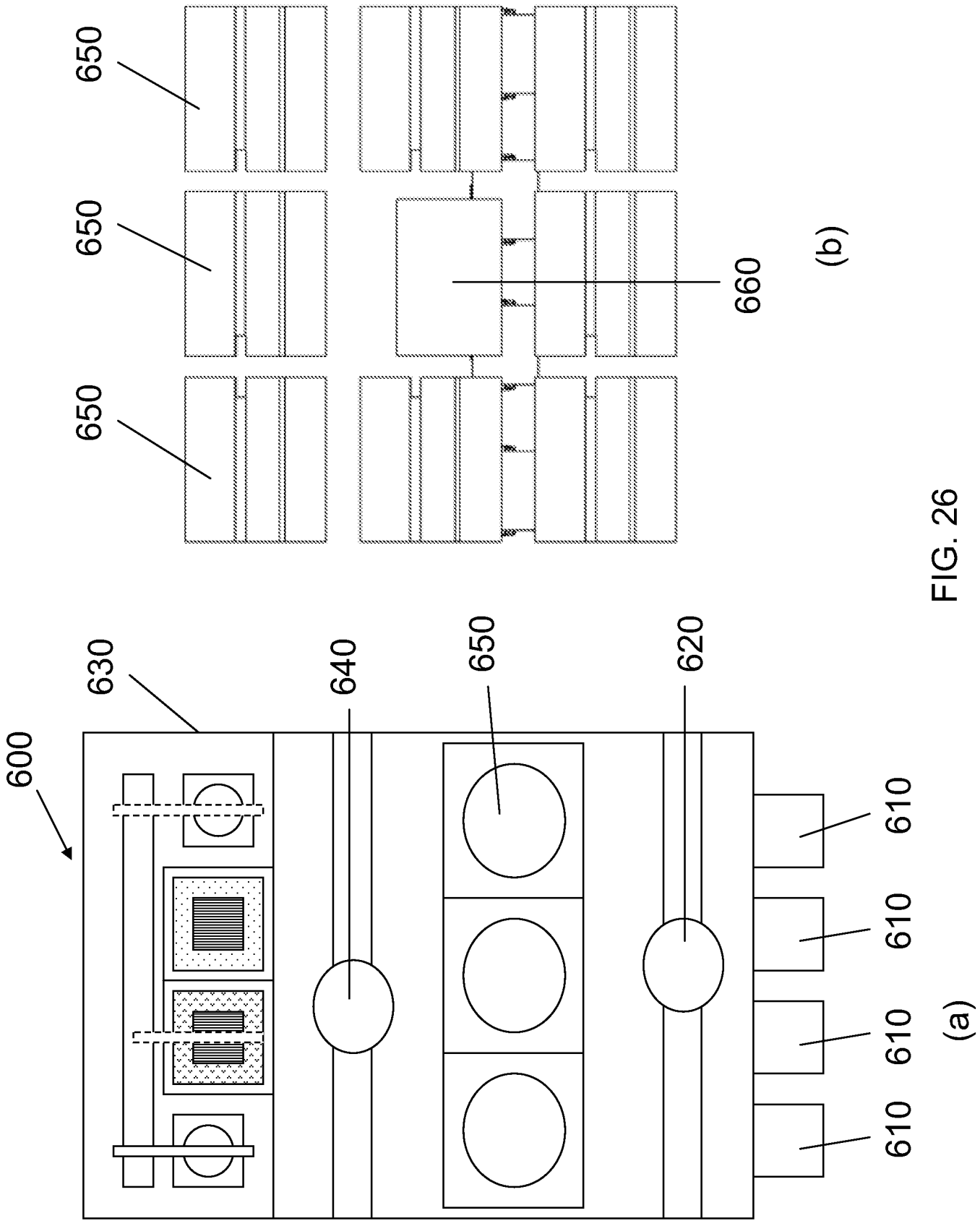



FIG. 26